



P-CHANNEL ENHANCEMENT MODE MOSFET WITH INTEGRATED SCHOTTKY DIODE

Product Summary

MOSFET						
BV _{DSS}	R _{DS(on)} Max	I _D				
-20V	85mΩ @ V _{GS} = -10V	-3.3A				
-20 V	125mΩ @ $V_{GS} = -4.5V$	-2.8A				
	SCHOTTKY DIODE					
V_{R}	V _{F Max}	lo				
20V	400mV @ I _F = 0.5A	1.0A				
200	470mV @ I _F = 1.0A	1.0A				

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- Power Management Functions
- Backlighting

Features and Benefits

- Low Input Capacitance
- MOSFET with Low R_{DS(ON)} Minimize Conduction Losses
- Schottky Diode with Low Forward Voltage Drop
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

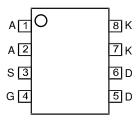
https://www.diodes.com/quality/product-definitions/

Mechanical Data

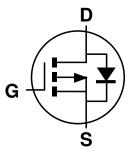
- Package: SO-8
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 (a)
- Weight: 0.074 grams (Approximate)



Top View



Top View







D1 Schottky Diode

Ordering Information (Note 4)

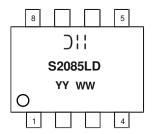
Dort Number	Dookono	Packing		
Part Number	Package	Qty.	Carrier	
DMS2085LSD-13	SO-8	2,500	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



⊃¦¦ = Manufacturer's Marking S2085LD = Product Type Marking Code YYWW = Date Code Marking YY or YY = Year (ex: 21 = 2021) WW = Week (01 to 53)

Maximum Ratings - P-CHANNEL MOSFET - Q1 (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V _{DSS}	-20	V		
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current (Note 6) V _{GS} = 10V		lσ	-3.3 -2.7	Α	
		I _D	-4.3 -3.4	Α	
Maximum Body Diode Forward Current (Note 6)	Is	-1.5	Α		
Pulsed Drain Current (10µs Pulse, Duty Cycle =	I _{DM}	-11.2	Α		
Avalanche Current (Note 7) L = 0.1mH			I _{AS}	-12	Α
Avalanche Energy (Note 7) L = 0.1mH			Eas	7	mJ

Maximum Ratings – SCHOTTKY – D1 (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	Vrrm Vrwm Vr	20	٧
Average Rectified Output Current (Note 7, t<10s)	lo	1	Α
Peak Repetitive Forward Current (Note 7, t<10s)	IFRM	2	Α
Non-Repetitive Peak Forward Surge Current (Note 7, t<10s) Single Half Sine-Wave Superimposed on Rated Load	IFSM	20	А

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Total Daway Dissination (Note 5)	T _A = +25°C	Б	1.1	W	
Total Power Dissipation (Note 5)	T _A = +70°C	P_D	0.7		
Thormal Bosistanes, Junction to Ambient (Note 5)	Steady State	D	108	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	R _θ ЈА	65	°C/VV	
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	D-	1.8	W	
Total Fower Dissipation (Note o)	$T_A = +70$ °C	P_D	1.0	v V	
Thermal Begintanes, Junction to Ambient (Note 6)	Steady State	Devi	78	°C/W	
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	Reja	50		
Thermal Resistance, Junction to Case (Note 6)	_	Rejc	22		
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

^{6.} Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

^{7.} I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25$ °C.



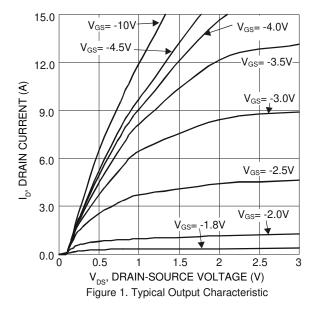
Electrical Characteristics P-Channel Q1 (@TA = +25°C, unless otherwise specified.)

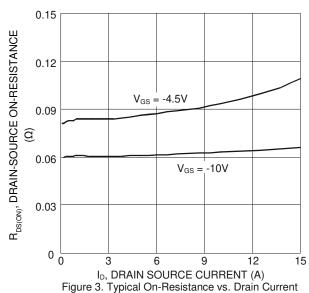
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current	IDSS	_	_	-1	μΑ	V _{DS} = -20V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(th)}	-0.5	-1.5	-2.2	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
Static Dunin Course On Besistance	D		70	85	0	V _{GS} = -10V, I _D = -3.05A
Static Drain-Source On-Resistance	RDS(ON)		100	125	mΩ	V _{GS} = -4.5V, I _D = -1.50A
Diode Forward Voltage	V_{SD}		-0.8	-1.0	٧	$V_{GS} = 0V, I_{S} = -1.0A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss		353	_		V _{DS} = -15V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	Coss		49	_	pF	
Reverse Transfer Capacitance	C _{rss}		41	_		I = I.UVIDZ
Gate Resistance	Rg		6.2	_	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge (Vgs = -4.5V)	Qg		3.7	_		
Total Gate Charge (V _{GS} = -10V)	Q_g		7.8	_	 C	\/aa 45\/ la 04
Gate-Source Charge	Qgs		1.1	_	nC	VDS = -15V, ID = -3A
Gate-Drain Charge	Q_{gd}		1.3	_		
Turn-On Delay Time	tD(on)		3.3	_		
Turn-On Rise Time	tr		3.0	_		$V_{DS} = -15V, R_{L} = 15\Omega$
Turn-Off Delay Time	t _{D(off)}		14	_	ns	$V_{GS} = -10V$, $R_{G} = 6\Omega$
Turn-Off Fall Time	t _f	_	6.8	_		
Body Diode Reverse Recovery Time	trr	_	33		ns	Is = -3.05A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Qrr		46		nC	Is = -3.05A, dI/dt = 100A/µs

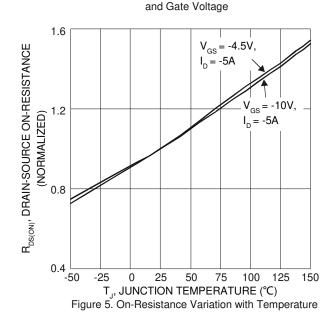
Notes: 8. Short duration pulse test used to minimize self-heating effect.

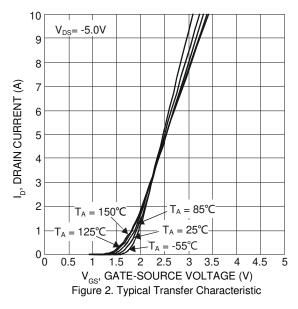
^{9.} Guaranteed by design. Not subject to product testing.

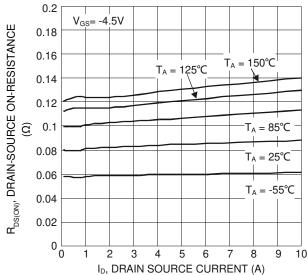












I_D, DRAIN SOURCE CURRENT (A)
Figure 4. Typical On-Resistance vs. Drain Current
and Temperature

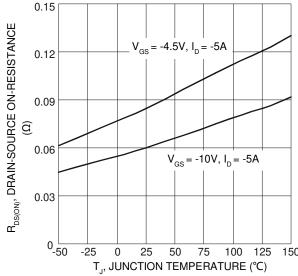


Figure 6. On-Resistance Variation with Temperature



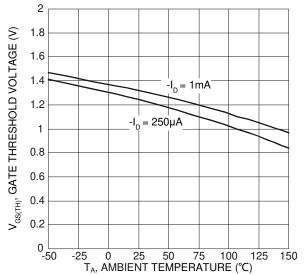


Figure 7. Gate Threshold Variation vs. Ambient Temperature

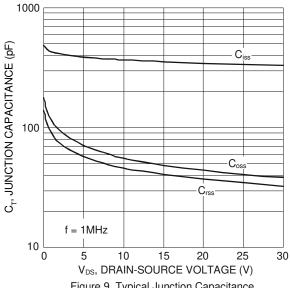
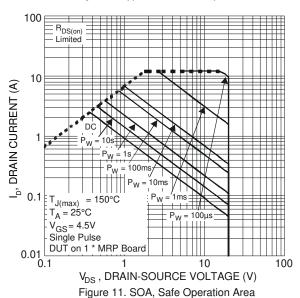


Figure 9. Typical Junction Capacitance



10 9 Is, SOURCE CURRENT (A) 7 6 $T_A = 150^{\circ}C$ _T_A = 125°C 3 25°C $T_A = 85^{\circ}C$ 2 -55°C 1 0 0 $\begin{array}{cccc} 0.3 & 0.6 & 0.9 & 1.2 \\ V_{\text{SD}}, \text{SOURCE-DRAIN VOLTAGE (V)} \end{array}$ 1.5

Figure 8. Diode Forward Voltage vs. Current

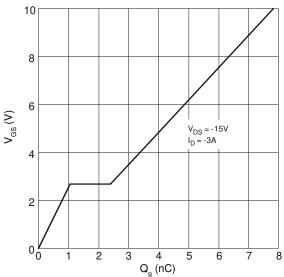


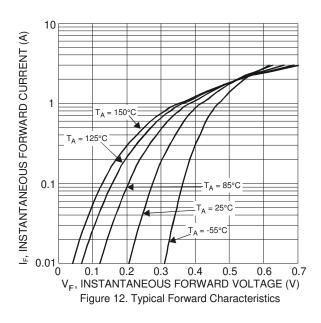
Figure 10. Gate-Charge Characteristics

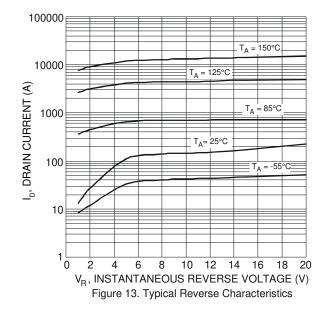


Electrical Characteristics - SCHOTTKY - D1 (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 10)	V _{(BR)R}	20	35		V	I _R = 1mA
Forward Voltage (Note 10)	VF		_	0.40 0.47	V	IF = 0.5A IF = 1.0A
Reverse Current (Note 10)	IR	_	30	80	μA	V _R = 20V

Note: 10. Short duration pulse test used to minimize self-heating effect.

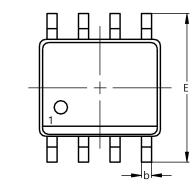


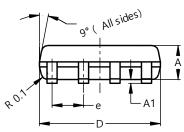


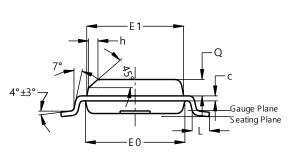


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.







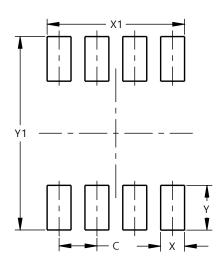
SO-8

SO-8						
Dim	Min	Max	Тур			
Α	1.40	1.50	1.45			
A 1	0.10	0.20	0.15			
Ь	0.30	0.50	0.40			
С	0.15	0.25	0.20			
D	4.85	4.95	4.90			
Е	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
е			1.27			
h			0.35			
L	0.62	0.82	0.72			
ø	0.60	0.70	0.65			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.





Dimensions	Value (in mm)
С	1.27
X	0.802
X1	4.612
Υ	1.505
V1	6 50



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